# MTM78E2B

**Dual N-channel MOS FET** 

For lithium-ion secondary battery protection circuit

### Overview

MTM78E2B is the MOS FET which is suitable for lithium ion secondary battery protection circuit and features low on-resistance by the leading-edge fine process and package techonology. Package is WSMini8-F1 which is suitable for battery packs for mobile application.

### Features

- Small surface mount package: WSMini8-F1-B (2.1 mm  $\times$  2.0 mm  $\times$  0.7 mm)
- Low on-resistance:  $R_{on} = 21.5 \text{ m}\Omega \text{ (typ.)} (I_D = 2 \text{ A}, V_{GS} = 4 \text{ V})$
- Drain common 2 elements
- 2.5V drive
- Halogen free package

### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Drain-source surrender voltage	V <sub>DSS</sub>	20	V
Gate-source surrender voltage	V <sub>GSS</sub>	±12	V
Drain current	ID	4.0	А
Peak drain current *1	I <sub>DP</sub>	40	А
Power dissipation	P <sub>D</sub> 1 *2	700	mW
	P <sub>D</sub> 2 *3	150	
Channel temperature	T <sub>ch</sub>	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

Note) \*1: t = 10 s, Duty cycle < 1%

\*2: Ceramic substrate (70 mm  $\times$  70 mm  $\times$  1.0 mm), dual operating.

\*3: Stand-alone (without the board)

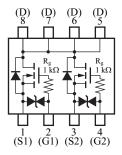
## Package

Code
WSMini8-F1-B

- Pin Name
  - 1: Source 15: Drain2: Gate 16: Drain3: Source 27: Drain
  - 4: Gate 2 8: Drain

Marking Symbol: 5A

### Internal Connection



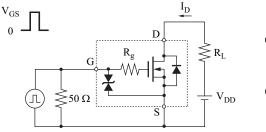
#### Symbol Conditions Min Unit Parameter Тур Max V Drain-source surrender voltage $I_D = 1.0 \text{ mA}, V_{GS} = 0$ 20 V<sub>DSS</sub> Drain-source cutoff current $I_{DSS}$ $V_{DS} = 20 V, V_{GS} = 0$ 1.0 μΑ $V_{GS} = \pm 12 \text{ V}, V_{DS} = 0$ Gate-source cutoff current $\pm 10$ μΑ I<sub>GSS</sub> 0.40 V $I_D = 1.0 \text{ mA}, V_{DS} = 10 \text{ V}$ 0.85 1.3 Gate threshold voltage $V_{TH}$ Drain-source ON resistance 1 $I_D = 2.0 \text{ A}, V_{GS} = 4.0 \text{ V}$ 21.5 25.0 mΩ R<sub>DS(on)</sub>1 $I_D = 1.5 \text{ A}, V_{GS} = 3.0 \text{ V}$ 30.0 Drain-source ON resistance 2 26.0 mΩ R<sub>DS(on)</sub>2 $I_D = 1.0 \text{ A}, V_{GS} = 2.5 \text{ V}$ 30.0 Drain-source ON resistance 3 R<sub>DS(on)</sub>3 36.0 mΩ Forward transfer conductance |Y<sub>fs</sub>| $I_D = 1.0 \text{ A}, V_{DS} = 10 \text{ V}$ 1.0 S Short-circuit input capacitance (Common source) 1100 pF Ciss Coss Short-circuit output capacitance (Common source) $V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$ 75 pF Reverse transfer capacitance (Common source) 70 C<sub>rss</sub> pF Turn-on delay time \* 0.20 t<sub>d(on)</sub> μs Rise time \* 0.50 t<sub>r</sub> $V_{DD} = 10 \text{ V}, V_{GS} = 4.0 \text{ V},$ μs $I_D = 1.0 \text{ A}, R_L = 10 \Omega$ Turn-off delay time \* 2.0 t<sub>d(off)</sub> μs Fall time \* 1.5 tf μs

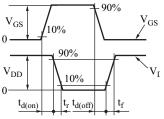
## Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

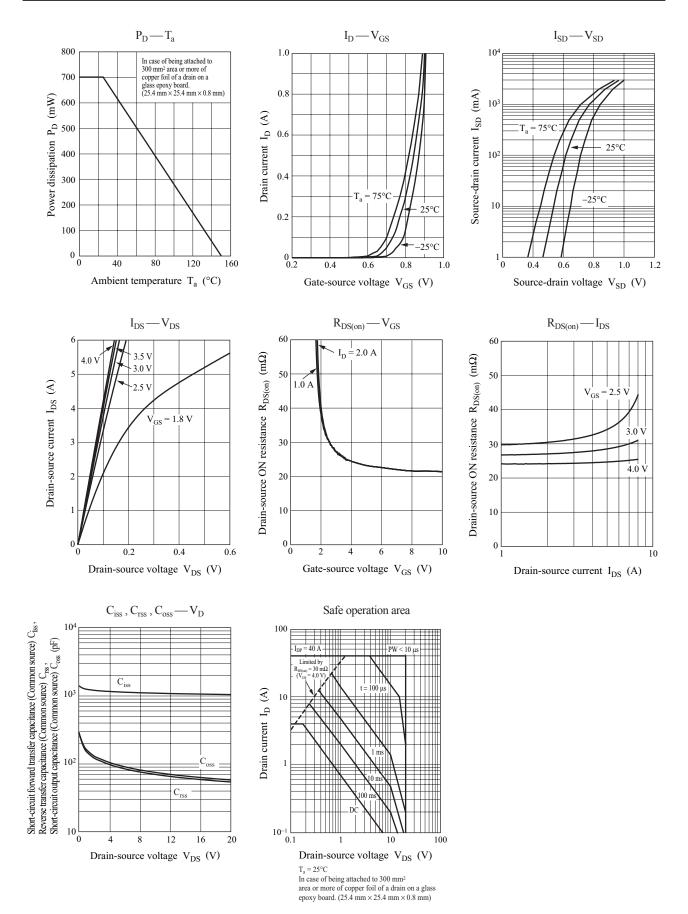
2. \*1: t = 10  $\mu$ s, Duty cycle < 1%

\*2: Measurement circuit





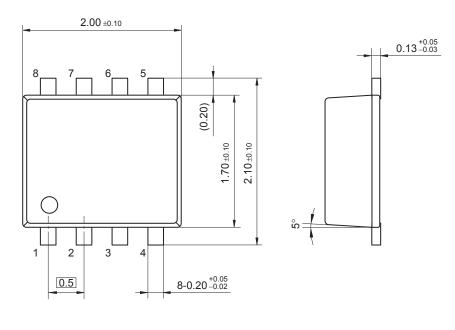
## **Panasonic**

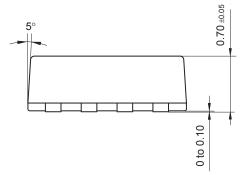


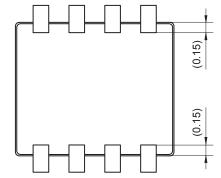
## **Panasonic**

## WSMini8-F1-B

Unit: mm







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